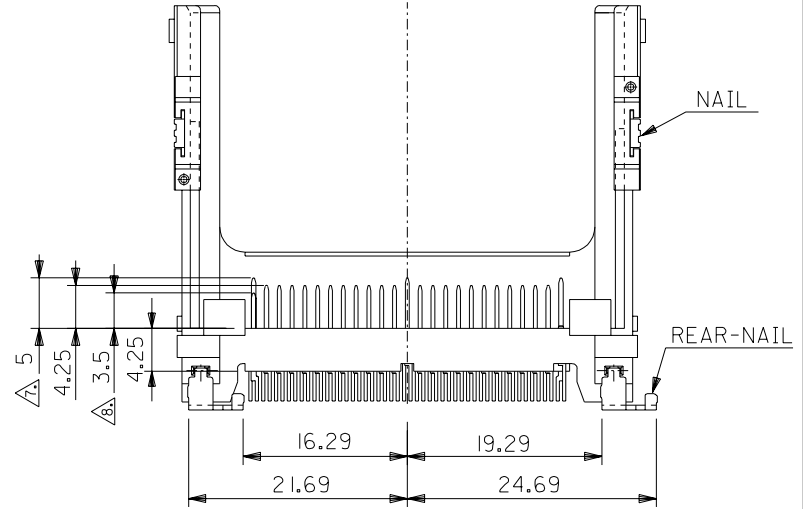
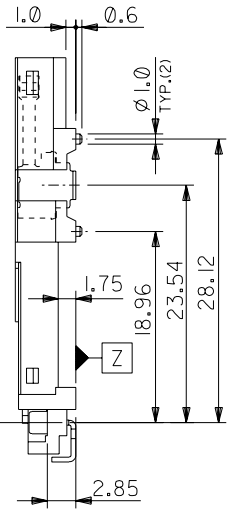
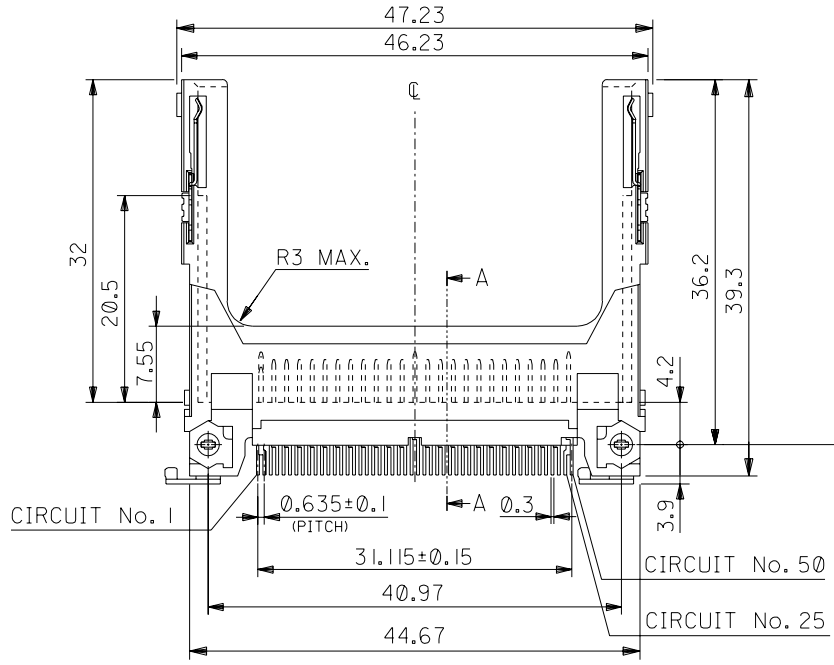
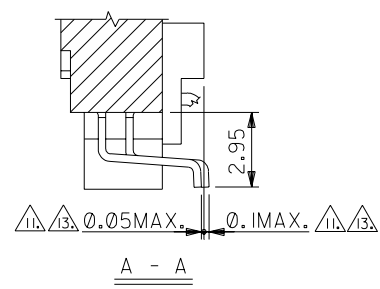
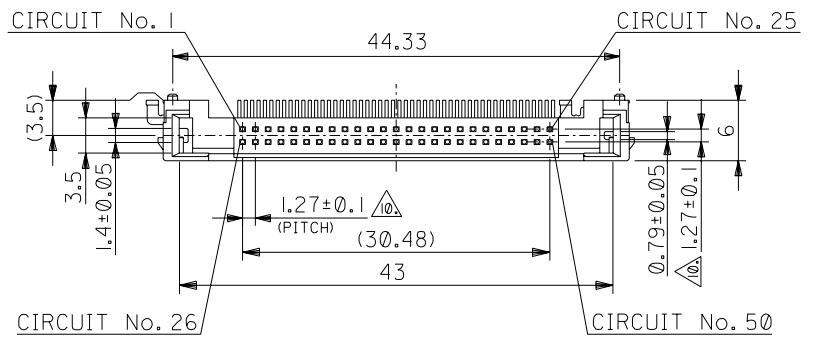


DWG. NO. SD-55359-015



SEMI-HARD TRAY PACKAGE	55359-5027
SOFT TRAY PACKAGE	55359-5029
PACKING TRAY FORM	MATERIAL NO.

DO NOT SCALE DRAWING	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	MATERIAL 材料 SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2 FINISH 仕上り SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2 WIRE RANGE 適用線被範圍 INS. RANGE 被覆外径	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未滿 ±0.2 10 OVER 30 UNDER 未滿 ±0.25 30 OVER 以上 ±0.3 ANGLE 角度 ±3°	SCALE DESIGN UNITS THIRD ANGLE PROJECTION DIMENSIONS: SHT REV REVISION ON CAD ONLY	DRAWN BY & DATE Y. Sakiyama '04/03/22 CHECKED BY & DATE H. Sasaki '04/03/22 APPROVED BY & DATE M. Sasaki '04/03/22 CAD FILENAME SD-55359-015.S01	TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE- MOLEX INCORPORATED	MATERIAL NO. DRAWING NO. SHEET NO.	SEE CHART SD-55359-015 1 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION. SIZE B
	8	7	7	6	5	4	3	2	2	2	EN-02J(097) MXJ-54			

A SD-55359-015.S01

DWG. NO. SD-55359-015

注) 1. 材質 MATERIAL

ハウジング: ガラス入りLCP UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
 ピン: リン青銅
 PIN: PHOSPHOR BRONZE
 ネール: リン青銅 (t0.3)
 NAIL: PHOSPHOR BRONZE (t0.3)
 リヤネール: リン青銅 (t0.48)
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)

2. メッキ仕様 PLATING

ピン
 接点部: パラジウムニッケル下地、金メッキ
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL PLATING
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL ALL OVER PLATING

ネール NAIL

接点部: 金メッキ
 CONTACT AREA: GOLD PLATING
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL ALL OVER PLATING

リヤネール REAR-NAIL

錫メッキ
 TIN PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL ALL OVER PLATING

3. 推奨基板厚 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.

4. 適合カード厚 RECOMMENDED CARD THICKNESS

接続部: 3.3±0.1
 CONNECTING AREA: 3.3±0.1

5. 適合カード幅 RECOMMENDED CARD WIDTH: 42.8±0.1

6. ハウジング色: 黒 HOUSING COLOR: BLACK

寸法適用極: 1,13,38,50
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.

寸法適用極: 25,26
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

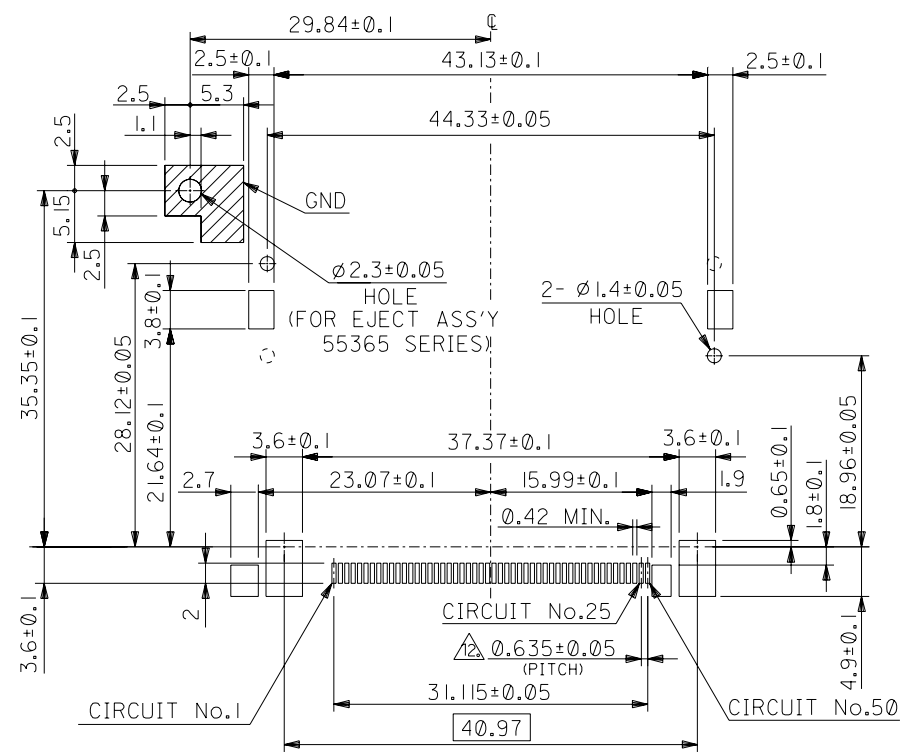
ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.

ピン根元に適用する。
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

- ソルダーテールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダーテールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
- 公差非累積 NON-CUMULATIVE
- テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.

14. 鉛フリー対応表 CORRESPONDENCE TABLE OF LEAD FREE

	SEMI-HARD TRAY PKG	SOFT TRAY PKG
半田品 LEAD CONTENT	55359 -5026	55359 -5021
鉛フリー品 LEAD FREE	55359 -5027	55359 -5029



基板推奨寸法 RECOMMENDED P.C.B. LAYOUT

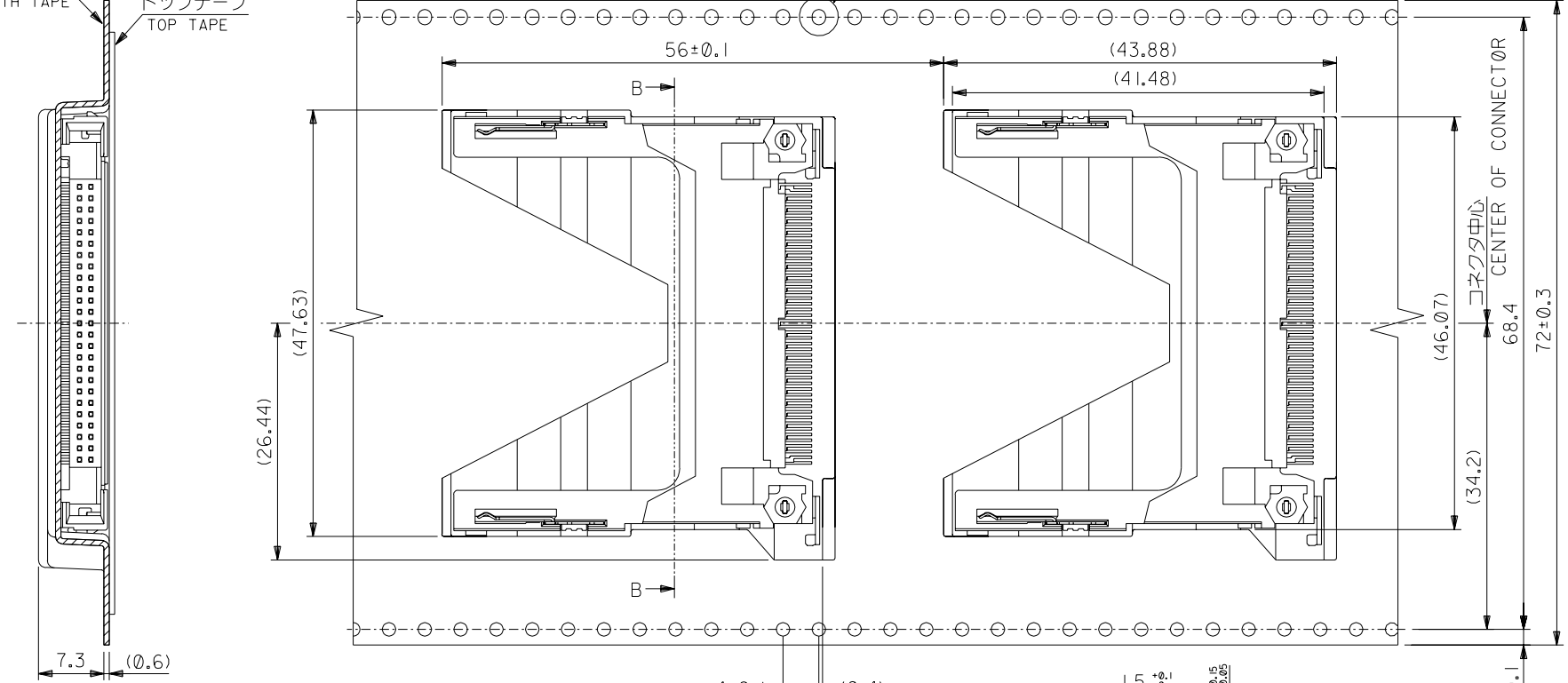
DO NOT SCALE DRAWING

EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	EC NO. DRAWN: CHK'g: APPR:	RELEASED '04/03/22 EC NO. J2004-3249 DRAWN: Y.SAKIYAMA CHK: MASASAO APPR: M.SASAO	MATERIAL 材料 注記参照 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未滿 ±0.2 10 OVER 以上 30 UNDER 未滿 ±0.25 30 OVER 以上 ±0.3	SCALE 1/1 DESIGN UNITS ㎜ □ INCH THIRD ANGLE PROJECTION	TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE-	DIMENSIONS: ㎜ □ INCH ㎟ ONLY SHT 2 REV 2
FINISH 仕上げ 注記参照 SEE NOTES	WIRE RANGE 適用電線範囲 —	ANGLE 角度 ±3°	MOLEX INCORPORATED		CAD FILENAME SD-55359-015.S02	MATERIAL NO. SEE CHART	DRAWING NO. SD-55359-015	SHEET NO. 2 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	

DWG. NO. SD-55359-016

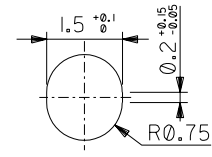
72巾テープ
72 WIDTH TAPE
トップテープ
TOP TAPE

引き出し方向
PULL OUT DIRECTION



断面 B-B
SECTION B-B

累積ピッチ: 40±0.2
ACCUMULATIVE PITCH: 40±0.2



A部詳細
DETAIL A

DO NOT SCALE DRAWING

EC NO.	DRWN:	CH'K:	APPR:	EC NO.	DRWN:	CH'K:	APPR:	EC NO.	DRWN:	CH'K:	APPR:	EC NO.	DRWN:	CH'K:	APPR:	EC NO.	DRWN:	CH'K:	APPR:
RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CH'K: MASASAO APPR: M.SASAO																			
REV	DESCRIPTION																		
0	SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2																		
	FINISH 仕上げ //																		
	WIRE RANGE 適用電線範囲 //																		
	INS. RANGE 被覆外径 //																		

MATERIAL 材料		SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2	
FINISH 仕上げ //		WIRE RANGE 適用電線範囲 //	
INS. RANGE 被覆外径 //			

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

55359-***78	
SCALE	DESIGN UNITS
---	<input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH
DRAWN BY & DATE Y. Sakiyama '04/03/22	
CHECKED BY & DATE H. Saito '04/03/22	
APPROVED BY & DATE H. Saito '04/03/22	
CAD FILENAME SD-55359-016.S02	

MODEL NO.	DIMENSIONS:	SHT	REV
	<input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY		REVISE ON CAD ONLY
THIRD ANGLE PROJECTION			
TITLE: EMBSTP PKG FOR CF CARD CONN. 50P HEADER ASSY -LEAD FREE-			
MOLEX MOLEX INCORPORATED			
MATERIAL NO.	DRAWING NO.	SHEET NO.	REV
SEE CHART	SD-55359-016	2 OF 2	B
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			